



Material Content Data Sheet



Sales Product Name		BSZ0501NSI		Issued		26. September 2017			
MA#		MA001300772							
Package		PG-TSDSON-8-26		Weight*		35.56 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.393	1.10	1.10	11040	11040	
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		102		
		non noble metal	zinc	7440-66-6	0.015	0.04		409	
		non noble metal	iron	7439-89-6	0.291	0.82		8176	
wire	non noble metal	non noble metal	copper	7440-50-8	11.804	33.20	34.07	331988	340675
		non noble metal	copper	7440-50-8	0.013	0.04	0.04	379	379
		encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		1000
plastics	plastics	epoxy resin	-	1.831	5.15		51509		
		inorganic material	silicondioxide	60676-86-0	15.914	44.77	50.02	447579	500088
		leadfinish	non noble metal	tin	7440-31-5	0.395	1.11	1.11	11117
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	571	571	
solder	noble metal	silver	7440-22-4	0.016	0.04		436		
		non noble metal	tin	7440-31-5	0.012	0.03		349	
		non noble metal	lead	7439-92-1	0.592	1.67	1.74	16660	17445
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		36		
		non noble metal	zinc	7440-66-6	0.005	0.01		142	
		non noble metal	iron	7439-89-6	0.101	0.28		2848	
		non noble metal	copper	7440-50-8	4.112	11.57	11.86	115659	118685
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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